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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of

Andrew Marshall

Serial No.: 10/007,332

TI-31484

Filed: 8-Nov-01

Art Unit: 2815

For: Thermal Coupling of Matched SOI Device Bodies

Examiner: Warren, M.E.

Conf. No.: 3238

**CERTIFICATION OF FACSIMILE TRANSMISSION**

I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office at 703-872-9306 on the date shown below:



Robin E. Barnum

August 30, 2004

Date

**FACSIMILE COVER SHEET**

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| <input checked="" type="checkbox"/> <b>FACSIMILE COVER SHEET</b>         | <input checked="" type="checkbox"/> <b>AMENDMENT</b> <u>116</u> ( <u>11</u> Pages) |
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| <input type="checkbox"/> <b>CONTINUATION APPN (# Pages)</b>              |  |
| <input type="checkbox"/> <b>DIVISIONAL APPN</b>                          |  |
| NAME OF INVENTOR(S): <u>Andrew Marshall</u>                              |  |
| TITLE OF INVENTION: <u>Thermal Coupling of Matched SOI Device Bodies</u> |  |
| TI FILE NO.: <u>TI-31484</u>   | DEPOSIT ACCT. NO.: <u>20-0668</u>  |
| FAXED: <u>8/30/04</u>  | DUE: <u>9/26/04</u>  |
| ATTY/SEC'Y: <u>RAK/reb</u>   |  |

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Texas Instruments Incorporated  
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Dallas, TX 75265

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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of: Andrew Marshall Docket No.: TI-31484

Serial No.: 10/007,332 Art Unit: 2815

Filed: 11/08/01 Examiner: Warren, M. E.

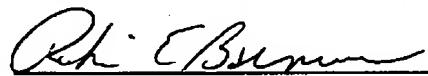
Title: Thermal Coupling of Matched SOI Device Bodies

**REPLY UNDER 37 C.F.R. §1.116 – EXPEDITED PROCEDURE  
TECHNOLOGY CENTER 2800**

August 30, 2004

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**CERTIFICATION OF FAX TRANSMITTAL**  
I hereby certify that the above correspondence is being facsimile  
transmitted to the Patent and Trademark Office on August 30, 2004.

  
Robin E. Barnum

Dear Sir:

In response to the Office Action, dated 07/26/2004, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to that Action. Charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.